

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-36. (Canceled).

37. (Currently Amended) A clad board for forming circuitry, the clad board being manufactured ~~through~~ by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

wherein said clad board ~~comprises~~ comprising:

a fiber sheet included in the pre-preg sheet;

resin material impregnated into the fiber sheet, the resin material ~~including~~ comprising at least one of a thermoplastic resin and a thermosetting resin having a semi-cured portion; and

a resin layer formed smoothly on the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein:

the fiber sheet comprises a first layer and a second layer, and

the density of the second layer is different from the density of the first layer.

38-39. (Canceled).

40. (Previously Presented) The clad board of claim 37, wherein the fiber sheet has a density ranging from 700 kg/m³ to 1000 kg/m³.

41. (Currently Amended) The clad board of claim 37,

wherein ~~the fiber sheet includes;~~

~~a the first layer of the fiber sheet is disposed at a surface of the fiber sheet; and~~

~~a the second layer of the fiber sheet has having a density lower than a density of the first layer.~~

42-46. Canceled

47. (Currently Amended) A The clad board of claim 37, for forming circuitry, the clad board manufactured by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being either a non-through-hole or a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet;

wherein said clad board comprises:

a fiber sheet included in the pre-preg sheet;

resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion; and

a resin layer formed smoothly on the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein the fiber sheet includes:

first and second layers disposed at respective surfaces of the fiber sheet; and

a third layer located between the first and second layers, the third layer having a density lower than respective densities of the first and second layers.

48-58. (Canceled).

59. (Currently Amended) The clad board of claim 37,

wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste including non-spherical-shaped conductive particles ~~a conductive particle shaped in non-spherical~~.

60-65. (Canceled).

66. (Currently Amended) A core board for a clad board for forming circuitry, said core board comprising:

a fiber sheet;

resin material impregnated into the fiber sheet, the resin material including at least one of a thermoplastic resin and a thermosetting resin having semi-cured portion; and

a resin layer formed on the fiber sheet, the resin layer being made of material identical to the resin material;

wherein:

the fiber sheet comprises a first layer and a second layer, and

the density of the second layer is different from the density of the first layer.

67-68. (Canceled).

69. (Previously Presented) The core board of claim 66, wherein the fiber sheet has a density ranging from 700 kg/m³ to 1000 kg/m³.

70. (Currently Amended) The core board of claim 66,

~~wherein the fiber sheet includes;~~

~~a the first layer disposed of the fiber sheet is at a surface of the fiber sheet; and~~

~~a the second layer of the fiber sheet has having a density lower than a density of the first layer.~~

71-75. Canceled

76. (Currently Amendment) A The core board of claim 66, for a clad board for forming circuitry, the core board comprising:

a fiber sheet;

resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion; and

a resin layer formed on the fiber sheet, the resin layer being made of material identical to the resin material;

wherein the fiber sheet includes;

first and second layers disposed at respective outermost sides of the fiber sheet; and

a third layer located between the first and second layers, the third layer having a density lower than respective densities of the first and second layers.

77-82. (Canceled).

83. (New) The clad board of claim 47, wherein the fiber sheet has a density ranging from 700 kg/m³ to 1000 kg/m³.

84. (New) The clad board of claim 47, wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

85. (New) The core board of claim 76, wherein the fiber sheet has a density ranging from 700 kg/m^3 to 1000 kg/m^3 .

86. (New) The clad board of claim 37, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

87. (New) The core board of claim 66, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.